



TET ESTEL AS
ESTONIA

October
2014

Series
TFI153S-1000

High Frequency Inverter grade
Capsule Thyristor
Type TFI153S-1000

Strong distributed amplified gate
and low turn-off time thyristor for
high frequency applications to 20 kHz

Maximum mean on-state current	I_{TAV}					1000 A
Maximum repetitive peak off-state and reverse voltage	U_{DRM}					800 ÷ 1300 V
Turn-off time	U_{RRM}					8, 10; 12,5 μs
	t_q					
U_{DRM}, U_{RRM}, V	800	900	1000	1100	1200	1300
Voltage code	8	9	10	11	12	13
$T_{vj}, °C$	- 60 ÷ 125					

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	TFI153S-1000	Conditions
I_{TAV}	Mean on-state current	A	1000 1370	$T_c=78 °C$, $T_c=55 °C$, 180° half-sine wave, 50 Hz
I_{TRMS}	RMS on-state current	A	1570	$T_c=78 °C$
I_{TSM}	Surge on-state current	kA	20,0 22,0	$T_{vj}=125°C$ $T_{vj}=25°C$ tp=10 ms $U_R=0$
I^2t	Limiting load integral	kA ² s	2000 2420	$T_{vj}=125°C$ $T_{vj}=25°C$
U_{DRM}, U_{RRM}	Repetitive peak off-state and reverse voltage	V	800÷1300	$T_j \min \leq T_{vj} \leq T_{jM}$ 180° half-sine wave, 50 Hz Gate open
U_{DSM}, U_{RSM}	Non-repetitive peak off-state and reverse voltage	V	880÷1400	$T_j \min \leq T_{vj} \leq T_{jM}$ 180° half-sine wave tp=10 ms, Single pulse Gate open
(di _T /dt) crit	Critical rate of rise of on-state current : non - repetitive repetitive	A/μs	1600 1000	$T_{vj}=125°C$; $U_D=0,67 U_{DRM}$, Gate pulse : 10V, 5 μs, 1 μs rise time, 10 μs
U_{RGM}	Peak reverse gate voltage	V	5	$T_j \min \leq T_{vj} \leq T_{jM}$
T_{stg}	Storage temperature	°C	-60÷80	
T_{vj}	Junction temperature	°C	-60÷125	

CHARACTERISTICS

U_{TM}	Peak on-state voltage	V	2,6	$T_{vj}=25°C$, $I_{TM}=3,14 I_{TAV}$
$U_{T(To)}$	Threshold voltage	V	1,55	$T_{vj}=125°C$
R_T	On-state slope resistance	mΩ	0,265	1,57 $I_{TAV} < I_T < 4,71 I_{TAV}$
I_{DRM} I_{RRM}	Repetitive peak off-state and reverse current	mA	100 100	$T_{vj}=125°C$, $U_D = U_{DRM}$ $U_R = U_{RRM}$

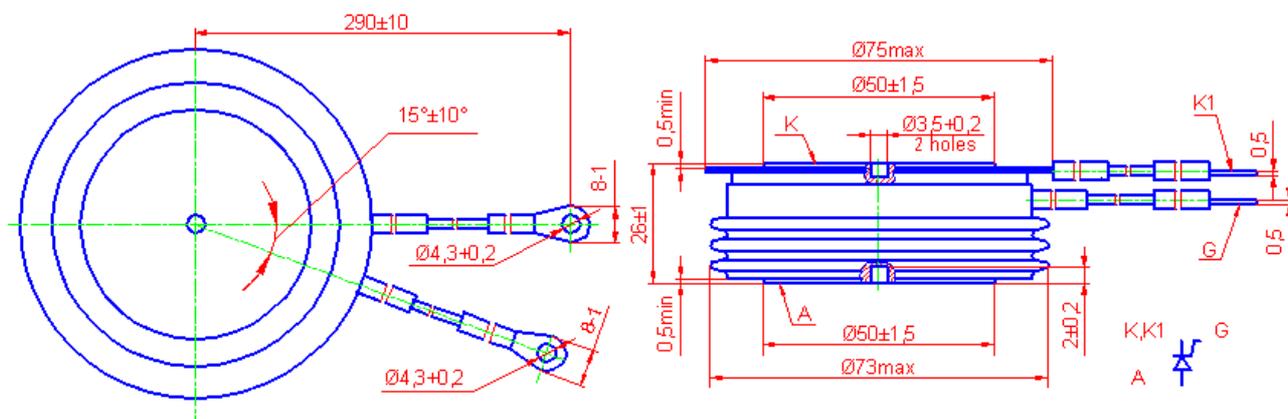
CHARACTERISTICS

Symbols and parameters		Units	TFI153S-1000	Conditions
I_L	Latching current	A	20	$T_{vj}=25^{\circ}\text{C}, U_D=12\text{V}$ Gate pulse : 10V, 5 Ω , 1 μs rise time, 10 μs
I_H	Holding current	A	0,5	$T_{vj}=25^{\circ}\text{C}, U_D=12\text{V}$, Gate open
U_{GT}	Gate trigger direct voltage	V	2,5 5,0	$T_{vj}=25^{\circ}\text{C}$, $T_{vj}=-60^{\circ}\text{C}$ $U_D=12\text{V}$
I_{GT}	Gate trigger direct current	A	0,35 0,90	$T_{vj}=25^{\circ}\text{C}$, $T_{vj}=-60^{\circ}\text{C}$
U_{GD}	Gate non-trigger direct voltage	V	0,25	$T_{vj}=125^{\circ}\text{C}, U_D = 0,67 U_{DRM}$
I_{GD}	Gate non-trigger direct current	mA	10	Direct gate current
t_{gd}	Delay time	μs	1,6	$T_{vj}=25^{\circ}\text{C}, U_D=500\text{V}$ $I_{TM} = 1000 \text{ A}$
t_{gt}	Turn-on time	μs	2,5	Gate pulse : 10V, 5 Ω , 1 μs rise time, 10 μs
t_q	Turn-off time	μs	8; 10; 12,5 10; 12,5; 16	$T_{vj}=125^{\circ}\text{C}, I_{TM}=1000 \text{ A}$ $di_R/dt = 10 \text{ A}/\mu\text{s}, U_R=100\text{V}$ $U_D = 0,67 U_{DRM}$ $du_D/dt=50 \text{ V}/\mu\text{s}$ $du_D/dt=200 \text{ V}/\mu\text{s}$
Q_{rr}	Recovered charge	μC	190	$T_{vj}=125^{\circ}\text{C}, I_{TM}=1000 \text{ A}$ $di_R/dt=50 \text{ A}/\mu\text{s}, U_R=100\text{V}$
t_{rr}	Reverse recovery time	μs	3,0	
I_{rrM}	Peak reverse recovery current	A	125	$T_{vj}=125^{\circ}\text{C}, U_D = 0,67 U_{DRM}$ Gate open
$(du_D/dt)_{crit}$	Critical rate of rise of off-state voltage	$\text{V}/\mu\text{s}$	500 1000	
R_{thjc}	Thermal resistance junction to case	$^{\circ}\text{C}/\text{W}$	0,021	Direct current, double side cooled

ORDERING

	TFI	153	S	1000	12	7	8	3	
	1	2	3	4	5	6	7	8	

- Fast thyristor with interdigitated gate structure.
- Design version.
- Strong distributed amplified gate.
- Mean on-state current, A.
- Voltage code (12=1200 V).
- Critical rate of rise of off-state voltage ($6 \geq 500 \text{ V}/\mu\text{s}$, $7 \geq 1000 \text{ V}/\mu\text{s}$).
- Group of turn-off time ($du_D/dt=50 \text{ V}/\mu\text{s}$, $8 \leq 12,5 \mu\text{s}$, $A4 \leq 10 \mu\text{s}$, $9 \leq 8 \mu\text{s}$).
- Group of turn-on time ($3 \leq 2,5 \mu\text{s}$).



Mounting force : 19 ÷ 28 kN
Weight : 580 grams